NOTES

1. MATERIALS:
  LEAD FRAME: COPPER 194FH, THK = 0.203 ± 0.008
  BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.

2. FINISH:
  LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1,
  250 TO 300 MICROINCHES (6.5um-7.6um) THICK,
  GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1
  (40 TO 80 MICROINCHES (1um-2um) THICK).
  BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
   AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220

DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE:
  ANGULAR: 0.5 degree
  XXX = 0.13
  XXXX = 0.01
  XX = 0.25
  X = 0.76

UNLESS OTHERWISE SPECIFIED
NAME DATE
DRAWN D. Abbe 8/1/11
CHECKED S. Swen 8/1/11
ENG APPR. S. Swen 8/1/11

SCALE: 10:1
WEIGHT: 500380

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